



Your PDF Guides

You can read the recommendations in the user guide, the technical guide or the installation guide for KINGSTON KHX2250C9D3T1K2-4GX. You'll find the answers to all your questions on the KINGSTON KHX2250C9D3T1K2-4GX in the user manual (information, specifications, safety advice, size, accessories, etc.). Detailed instructions for use are in the User's Guide.

User manual KINGSTON KHX2250C9D3T1K2-4GX
User guide KINGSTON KHX2250C9D3T1K2-4GX
Operating instructions KINGSTON KHX2250C9D3T1K2-4GX
Instructions for use KINGSTON KHX2250C9D3T1K2-4GX
Instruction manual KINGSTON KHX2250C9D3T1K2-4GX




Memory Module Specification

KHX2250C9D3T1K2/4GX
4GB (2GB 256M x 64-Bit x 2 pcs.) DDR3-2250MHz
CL9 240-Pin DIMM Kit

DESCRIPTION:
Kingston's KHX2250C9D3T1K2/4GX is a kit of two 256M x 64-bit (2GB) DDR3-2250MHz CL9 SDRAM (Synchronous DRAM) memory modules, based on sixteen 128M x 8-bit DDR3 FBGA components per module. Each module kit supports Intel® XMP (Extreme Memory Profiles). Total kit capacity is 4GB. Each module has been tested to run at DDR3-2250MHz at a low latency timing of 9-11-9 at 1.65V. The SPDs are programmed to JEDEC standard latency DDR3-1333MHz timing of 9-9-9 at 1.5V. Each 240-pin DIMM uses gold contact fingers and requires +1.5V. The JEDEC standard electrical and mechanical specifications are as follows:

FEATURES:

- JEDEC standard 1.5V ± 0.075V Power Supply
- VDDQ = 1.5V ± 0.075V
- 667MHz ICK for 1333Mbs/pcpin
- 8 independent internal bank
- Programmable CAS Latency: 6,7,8,9
- Preced CAS
- Programmable Additive Latency: 0, CL - 2, or CL - 1 clock
- Programmable CAS Write Latency (CWL) = 7 (DDR3-1333)
- 8-bit pre-fetch
- Burst Length: 8 (Interleave without any limit, sequential with starting address "000" only), 4 with rCCD = 4 which does not allow stream read or write (either on the fly using A12 or MRS)
- Bi-directional Differential Data Strobe
- Internal self calibration: Internal self calibration through ZQ pin (RZQ : 240 ohm ± 1%)
- On Die Termination using ODT pin
- Average Refresh Period 7.8µs at lower than TCASE: 85°C, 39µs at 85°C < TCASE: 95°C
- Asynchronous Reset
- PCB : Height 2.401" (61.00mm) w/ heat sink, double sided component



PERFORMANCE:

- CL (t_{RP}) 9 cycles
- Row Cycle Time (t_{RC}min) 49.5ns (min.)
- Refresh to Active/Refresh Command Time (t_{RF}min) 110ns
- Row Active Time (t_{RAS}min) 36ns (min.)
- Power 1.800 W (operating per module)
- UL Rating 94 V-0
- Operating Temperature 0° C to 85° C
- Storage Temperature -55° C to +100° C

Document No. 4805700-001.A00 07/22/10 Page 1



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Manual abstract:

) DDR3-2250MHz CL9 240-Pin DIMM Kit DESCRIPTION: Kingston's KHX2250C9D3T1K2/4GX is a kit of two 256M x 64-bit (2GB) DDR3-2250MHz CL9 SDRAM (Synchronous DRAM) memory modules, based on sixteen 128M x 8-bit DDR3 FBGA components per module. Each module kit supports Intel® XMP (Extreme Memory Profiles). Total kit capacity is 4GB. Each module has been tested to run at DDR3-2250MHz at a low latency timing of 9-11-9 at 1.65V. @@Each 240-pin DIMM uses gold contact fingers and requires +1.5V. @@@@4805700-001.A00 Page 2 .



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